

Company: Hirata Corporation  
President: Yuichiro Hirata  
Securities code: 6258  
Contact: Investor Relations and  
Public Relations Department  
(E-mail: [hirata\\_info@hirata.co.jp](mailto:hirata_info@hirata.co.jp))  
(URL: <http://www.hirata.co.jp>)

September 8, 2011

## **Announcement about development of new FOUP opener and wafer handling robot**

Hirata Corporation announced that we have developed the industry-leading 300mm FOUP opener and wafer handling robot that will be introduced to the semiconductor market this October.

We manufacture and sell various production systems in automotive, FPD (Flat Panel Display), semiconductor and home electrical appliance market. In the semiconductor production system market, we obtained trust and admiration from our customers by providing FOUP opener to open/close FOUP (wafer container), the wafer handling robot for both atmospheric and vacuum environment, EFEM that integrates all components and wafer sorter.

We believe that the new products introduced to the market will meet requests of both process equipment makers and device makers in semiconductor industry.

### **I. 300 mm FOUP Opener KWF - 12E2**

High throughput, cleanliness, ease of maintenance and improved functions will contribute to customers' productivity.

#### **1. Strong Points**

##### **1) Particle-free**

Cleanliness achieved by design based on airflow analysis requires no positive pressure of process equipment. It is adaptable for semiconductor products with next generation pattern size (22nm).

- Structure to separate drives from process equipment space
- Close FOUP door tightly to prevent particles to spread
- No positive pressure of process equipment to secure cleanliness by proper location of exhaust fan

##### **2) Auto-FOSB Compatible**

Open/close Auto-FOSB as standard feature

### **3) Battery-free**

New encoder adopted to eliminate encoder data backup battery.

Ease of maintenance is much improved.

### **4) Easy Installation**

Improved mounting/adjusting structure realizes easy/short installation.

(30% shorter compared to our previous model)

Improved mounting/adjusting structure realizes better installation repeatability and MTTR.

### **5) Max Speed**

Industry-leading operation speed (self-administered survey) will contribute to equipment's throughput. (1 second shorter than our conventional model).

### **6) N2 Purge Function**

Quick N2 purge function to accommodate traditional FOUP (option / the release will be by the end of 2011.)

The following options are available as well.

- 200mm open cassette compatible (with adapter)
- FOUP 180 degrees rotation function (the release will be by the end of 2011)

## **2. Appearance**



## **II. Wafer Handling Robot AR-W n 1 8 0 C L series**

### **1. Strong Points**

High performance and rich variety contribute to customer's productivity.

### 1) Various Arm Lineup

Single arm, twin arm, flip axis, wrist axis and long Z stroke (940mm) are lined up.

### 2) Battery-free

New encoder adopted to eliminate encoder data backup battery.

Ease of maintenance is much improved.

### 3) High Throughput

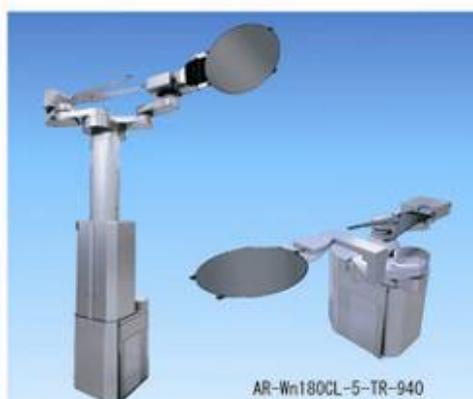
Hirata original motion control is enabled for seamless motion.

PUT/GET time is reduced by 35% compared to our conventional model.

### 4) Vibration Control

Hirata original vibration control technology suppresses mechanical vibration.

## 2. Appearance



## III. Effect on Business

We expect that the new products will increase the sales and contribute to our business performance after March 2013.

## IV. Display at the Exhibition

We plan to exhibit a sorter integrating the new products during SEMICON Japan 2011, the international semiconductor exhibition taking place at Makuhari Messe in Chiba from 12/7 to 12/9.

End